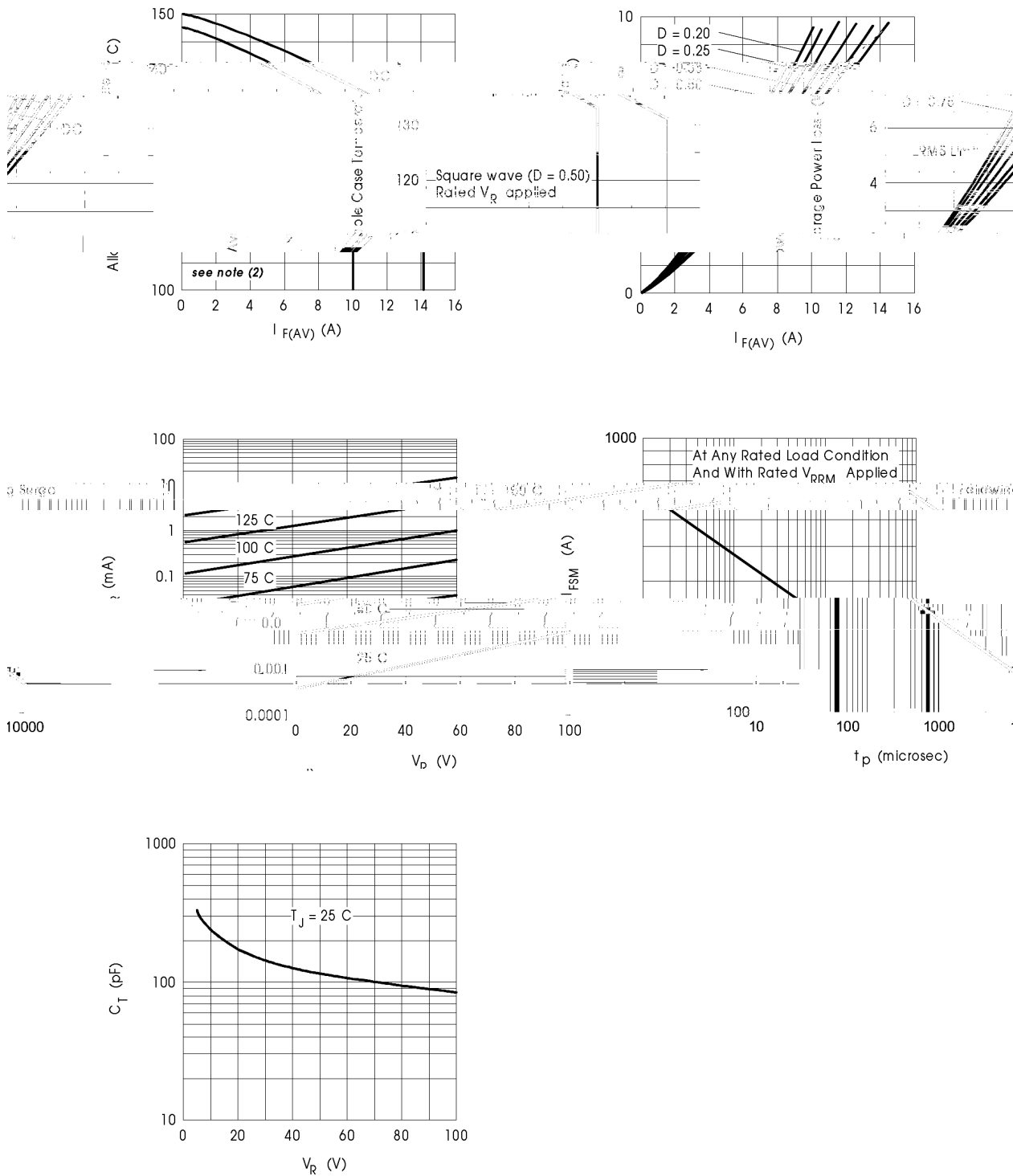
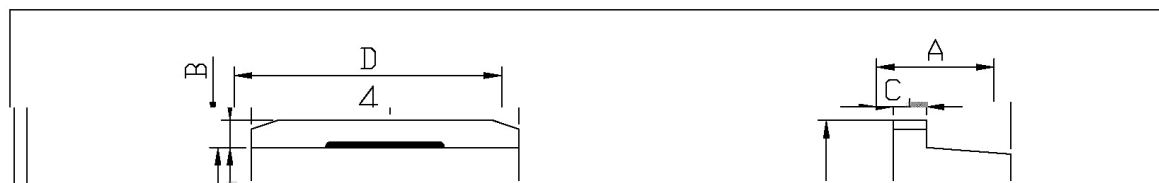


Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	100	V
Working Peak Reverse Voltage	V_{RWM}	100	V
Peak Repetitive Forward Current	I_{FRM}	20	A
Average Rectified Forward Current	$I_{F(AV)}$	10	A
	$I_{F(AV)} (total)$	20	A
Non Repetitive Peak Surge Current	I_{FSM}	150	A
Peak Repetitive Reverse Surge Current	I_{RRM}	0.5	A
Thermal Resistance Junction to Case	R_{JC}	2.0	/W
Junction Temperature Range	T_j	175	
Storage Temperature Range	T_{stg}	-55~175	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Peak Forward Voltage	V_{FM}	$I_F=10A(T_C=25^{\circ}C)$			0.85	V
		$I_F=10A(T_C=125^{\circ}C)$			0.7	V
		$I_F=20A(T_C=25^{\circ}C)$			0.95	V
		$I_F=20A(T_C=125^{\circ}C)$			0.85	V
Instantaneous Reverse Current	I_{RM}	$V_R=100V(T_C=25^{\circ}C)$			0.15	mA
		$V_R=100V(T_C=125^{\circ}C)$			150	mA
Voltage Rate of Change	dv/dt				10000	V/ s

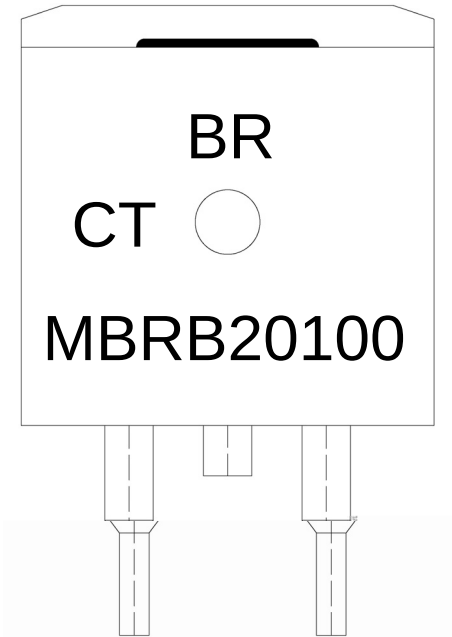




单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeter	
	Min	Max		Min	Max
A	4.30	4.70	E	9.00	9.40
B	1.00	1.40	e1	2.34	2.74
b	0.70	0.90	e2	4.88	5.28
b1	1.15	1.35	L1	15.00	16.0
b2	0.40	0.60	L2	2.24	2.9
C	1.20	1.40	L3	1.20	1.4
D	9.80	10.20			

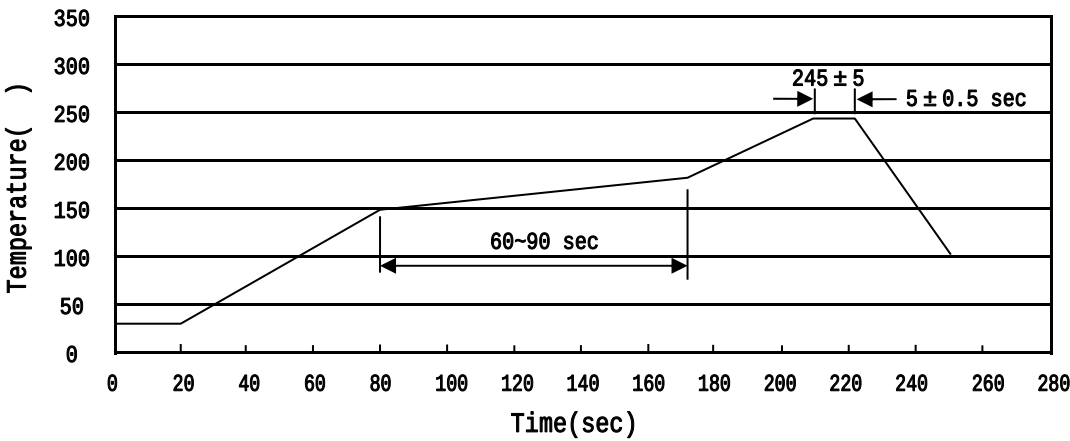
TH-262



BR	
MBRB20100	
CT:	

Note:	
BR:	Company Code
MBRB20100	Product Type Code
CT:	Internal Structure
****:	Lot No. Code, code change with Lot No.

Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ REEL

Package Type	Units					Dimension (unit mm ³)		
TO-263	800	1	800	6	4,800	13" ×24	360×360×50	380×335×366

/ TUBE

Package Type	Units					Dimension (unit mm ³)		
TO-263	50	20	1,000	5	5,000	532×33×7.0	555×164×50	575×290×180